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(54) VACUUM TRANSFER DEVICE FOR SEMICONDUCTOR SUBSTRATE

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**PURPOSE:** To sweep away problems caused by separation of resist that flew out to the side and the reverse of a semiconductor substrate by arranging the constitution such that the periphery of the side and the reverse of a semiconductor substrate and the lower cup of a vacuum vessel may not contact with each other.

**CONSTITUTION:** There are a vacuum container 1 for a semiconductor manufacturing device, an upper cup 2, a semiconductor substrate to which resist is applied, a lower cup 4, and a pusher 5 to elevate the semiconductor substrate 3. And by providing a groove 7 around the bottom of the lower cup 4, the contact between the periphery of the side and the reverse of the semiconductor substrate 3 and the lower cup 4 is removed. Accordingly, resist that flew out to the side and the reverse of the semiconductor substrate 3 adheres to the lower cup 4 and never comes off, and etching failure and ion implantation failure also disappears. Hereby, it can sweep away problems by separation of resist adhered to the side and reverse of the semiconductor substrate.

